Document Title

64Kx8 bit Low Power CMOS Static RAM

Revision History

Revision No.	History	Draft Data	Remark
0.0	Initial draft	January 10th 1998	Advance

64Kx8 bit Low Power CMOS Static RAM

FEATURES

- Process Technology : 0.4 µm CMOS
- Organization : 64Kx8
- Power Supply Voltage : Single 5V ±10%
- Low Data Retention Voltage : 2V(Min)
- Three state output and TTL Compatible
- Package Type : 32-TSOP I -0820F

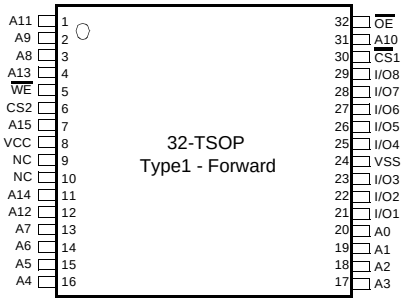
GENERAL DESCRIPTION

The KM68512B family is fabricated by SAMSUNG ′s advanced CMOS process technology. The family support various operating temperature ranges and small package type for user flexibility of system design. The family also support low data retention voltage for battery back-up operation with low data retention current.

PRODUCT FAMILY

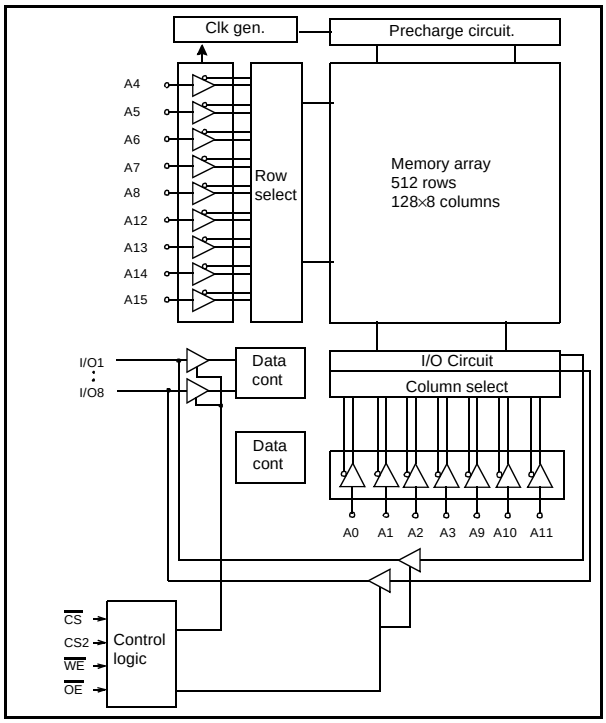
Product Family	Operating Temperature	Vcc Range	Speed(ns)	Power Dissipation		PKG Type
				Standby (I_{SB1}, Max)	Operating (I_{CC2}, Max)	
KM68512BL-L	Commercial(0~70°C)	5V±0.5V	55/70	10µA	60mA	32-TSOP1-F
KM68512BLI-L	Industrial(-40~85°C)		70	15µA		

PIN DESCRIPTION



Name	Function
A_0~A_{15}	Address Inputs
$\overline{WE}$	Write Enable Input
$\overline{CS_1}$, CS_2	Chip Select Inputs
$\overline{OE}$	Output Enable Input
I/O_1~I/O_8	Data Inputs/Outputs
Vcc	Power
Vss	Ground
N.C	No Connection

FUNCTIONAL BLOCK DIAGRAM



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PRODUCT LIST

Commercial Temperature Product (0~70°C)		Industrial Temperature Products (-40~85°C)	
Part Name	**Function**	**Part Name**	**Function**
KM68512BLT-5L	32-TSOP1-F, 55ns, LL-pwr	KM68512BLTI-7L	32-TSOP1-F, 70ns, LL-pwr
KM68512BLT-7L	32-TSOP1-F, 70ns, LL-pwr		

FUNCTIONAL DESCRIPTION

$\overline{CS_1}$	CS_2	$\overline{OE}$	$\overline{WE}$	I/O Pin	Mode	Power
H	X[1)]	X[1)]	X[1)]	High-Z	Deselected	Standby
X[1)]	L	X[1)]	X[1)]	High-Z	Deselected	Standby
L	H	H	H	High-Z	Output Disabled	Active
L	H	L	H	Dout	Read	Active
L	H	X	L	Din	Write	Active

1. X means don't care.(Must be low or high state)

ABSOLUTE MAXIMUM RATINGS [1)]

Item	Symbol	Ratings	Unit	Remark
Voltage on any pin relative to Vss	V_{IN},V_{OUT}	-0.5 to 7.0	V	-
Voltage on Vcc supply relative to Vss	V_{CC}	-0.5 to 7.0	V	-
Power Dissipation	P_D	1.0	W	-
Storage temperature	T_{STG}	-65 to 150	°C	-
Operating Temperature	T_A	0 to 70	°C	KM68512BL
		-40 to 85	°C	KM68512BLI
Soldering temperature and time	T_{SOLDER}	260°C, 10sec(Lead Only)	-	-

1. Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation should be restricted to recommended operating condition. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS [1)]

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	Vcc	4.5	5.0	5.5	V
Ground	Vss	0	0	0	V
Input high voltage	V_{IH}	2.2	-	Vcc+0.5V[2)]	V
Input low voltage	V_{IL}	-0.5[3)]	-	0.8	V

Note
1. Commercial Product : T_A=0 to 70°C, unless otherwise specified
   Industrial Product : T_A=-40 to 85°C, unless otherwise specified
2. Overshoot : V_{CC}+3.0V in case of pulse width≤30ns
3. Undershoot : -3.0V in case of pulse width≤30ns
4. Overshoot and undershoot is sampled, not 100% tested

CAPACITANCE [1)](f=1MHz, T_A=25°C)

Item	Symbol	Test Condition	Min	Max	Unit
Input capacitance	C_{IN}	V_{IN}=0V	-	6	pF
Input/Output capacitance	C_{IO}	V_{IO}=0V	-	8	pF

1. Capacitance is sampled, not 100% tested

DC AND OPERATING CHARACTERISTICS

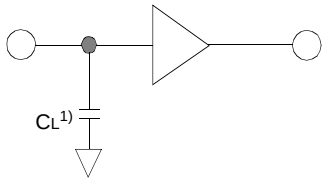
Item	Symbol	Test Conditions		Min	Typ	Max	Unit
Input leakage current	I_{LI}	V_{IN}=Vss to Vcc		-1	-	1	µA
Output leakage current	I_{LO}	$\overline{CS_1}$=V_{IH} or CS_2=V_{IL} or $\overline{OE}$=V_{IH} or $\overline{WE}$=V_{IL}, V_{IO}=Vss to Vcc		-1	-	1	µA
Operating power supply	I_{CC}	I_{IO}=0mA, $\overline{CS_1}$=V_{IL}, CS_2=V_{IH}, V_{IN}=V_{IL} or V_{IH}, Read		-	7	10	mA
Average operating current	I_{CC1}	Cycle time=1§Á, 100% duty, I_{IO}=0mA, $\overline{CS_1}$≤0.2V, CS_2≥Vcc-0.2V, V_{IN}≤0.2V or V_{IN}≥Vcc -0.2V	Read	-	-	5	mA
			Write	-	-	30	mA
	I_{CC2}	Cycle time=Min, 100% duty, I_{IO}=0mA, $\overline{CS_1}$=V_{IL}, CS_2=V_{IH}, V_{IN}=V_{IL} or V_{IH}		-	-	60	mA
Output low voltage	V_{OL}	I_{OL}=2.1mA		-	-	0.4	V
Output high voltage	V_{OH}	I_{OH}=-1.0mA		2.4	-	-	V
Standby Current(TTL)	I_{SB}	$\overline{CS_1}$=V_{IH}, CS_2=V_{IL}, Other inputs =V_{IL} or V_{IH}		-	-	3	mA
Standby Current (CMOS)	I_{SB1}	$\overline{CS_1}$≥Vcc-0.2V, CS_2≥Vcc-0.2V or CS_2≤0.2V		-	1	10[1)]	µA

1. Industrial product = 15µA

AC OPERATING CONDITIONS

TEST CONDITIONS (Test Load and Input/Output Reference)

Input pulse level : 0.8 to 2.4V
Input rising and faling time : 5ns
Input and output reference voltage :1.5V
Output load(see right) : C_L=100pF+1TTL



1. Including scope and jig capacitance

AC CHARACTERISTICS (Vcc=4.5~5.5V, KM68512B Family : T_A=0 to 70°C, KM68512BI Family : T_A=-40 to 85°C)

Parameter List		Symbol	Speed Bins				Units
			55ns		70ns		
			Min	Max	Min	Max	
Read	Read cycle time	t_{RC}	55	-	70	-	ns
	Address access time	t_{AA}	-	55	-	70	ns
	Chip select to output	t_{CO}	-	55	-	70	ns
	Output enable to valid output	t_{OE}	-	25	-	35	ns
	Chip select to low-Z output	t_{LZ}	10	-	10	-	ns
	Output enable to low-Z output	t_{OLZ}	5	-	5	-	ns
	Chip disable to high-Z output	t_{HZ}	0	20	0	25	ns
	Output disable to high-Z output	t_{OHZ}	0	20	0	25	ns
	Output hold from address change	t_{OH}	10	-	10	-	ns
Write	Write cycle time	t_{WC}	55	-	70	-	ns
	Chip select to end of write	t_{CW}	45	-	60	-	ns
	Address set-up time	t_{AS}	0	-	0	-	ns
	Address valid to end of write	t_{AW}	45	-	60	-	ns
	Write pulse width	t_{WP}	40	-	55	-	ns
	Write recovery time	t_{WR}	0	-	0	-	ns
	Write to output high-Z	t_{WHZ}	0	20	0	25	ns
	Data to write time overlap	t_{DW}	20	-	30	-	ns
	Data hold from write time	t_{DH}	0	-	0	-	ns
	End write to output low-Z	t_{OW}	5	-	5	-	ns

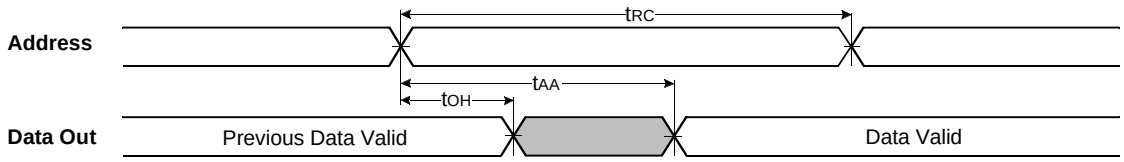
DATA RETENTION CHARACTERISTICS

Item	Symbol	Test Condition		Min	Typ	Max	Unit
Vcc for data retention	V_{DR}	$\overline{CS_1}$[1]≥Vcc-0.2V		2.0	-	5.5	V
Data retention current	I_{DR}	Vcc=3.0V, $\overline{CS_1}$≥Vcc-0.2V	KM68512BL-L	-	0.5	10	µA
			KM68512BLI-L	-	-	15	
Data retention set-up time	t_{SDR}	See data retention waveform		0	-	-	ms
Recovery time	t_{RDR}			5	-	-	

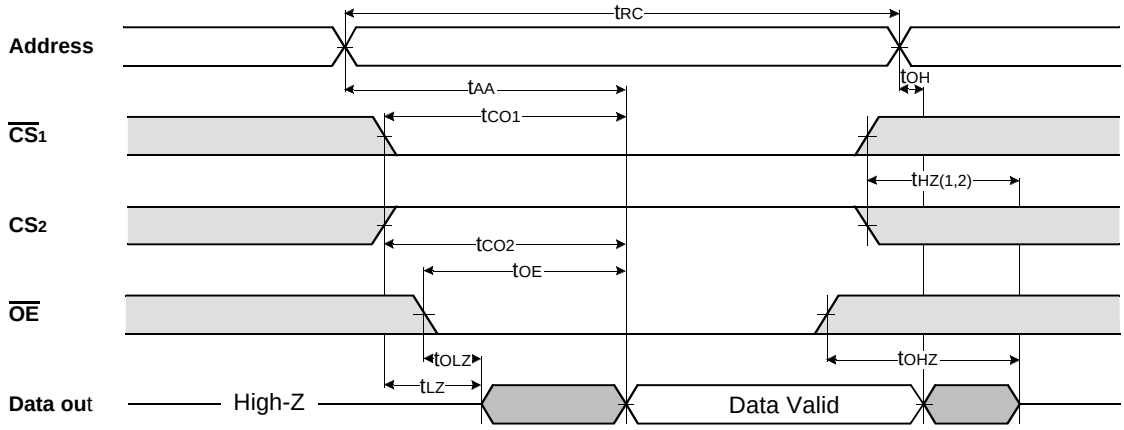
1. $\overline{CS_1}$≥Vcc-0.2V, CS_2≥Vcc-0.2V($\overline{CS_1}$ controlled) or CS_2≤0.2V(CS_2 controlled).

TIMMING DIAGRAMS

TIMING WAVEFORM OF READ CYCLE(1) (Address Controlled, $\overline{CS}$=$\overline{OE}$=V_{IL}, $\overline{WE}$=V_{IH})



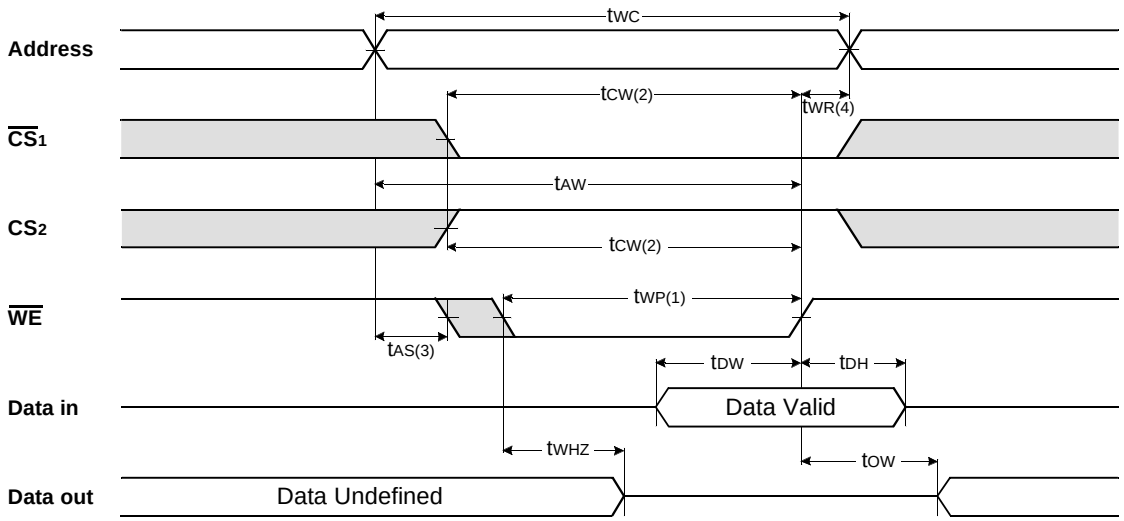
TIMING WAVEFORM OF READ CYCLE(2) ($\overline{WE}$=V_{IH})



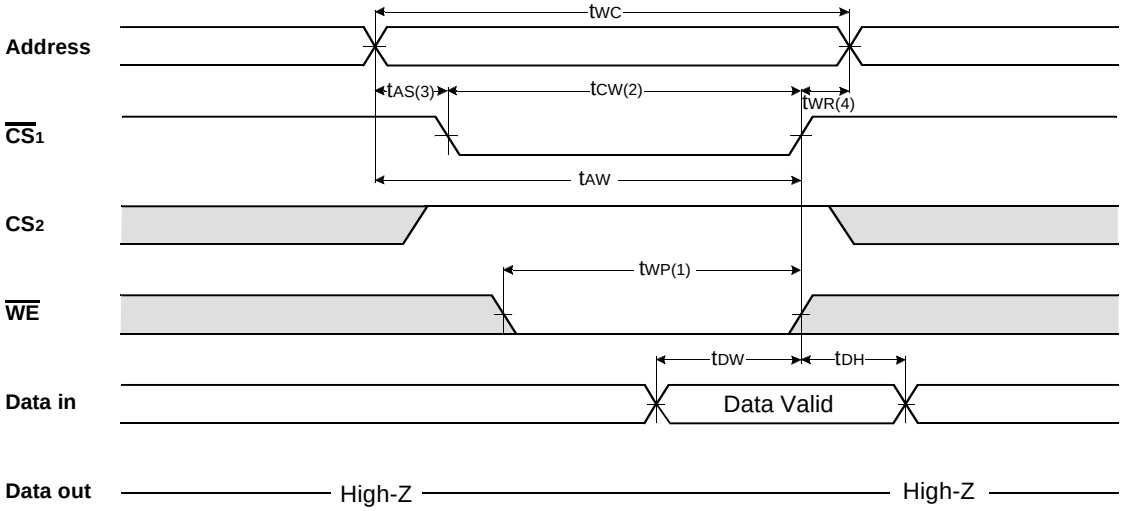
NOTES (READ CYCLE)

1. t_{HZ} and t_{OHZ} are defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels.
2. At any given temperature and voltage condition, t_{HZ}(Max.) is less than t_{LZ}(Min.) both for a given device and from device to device interconnection.

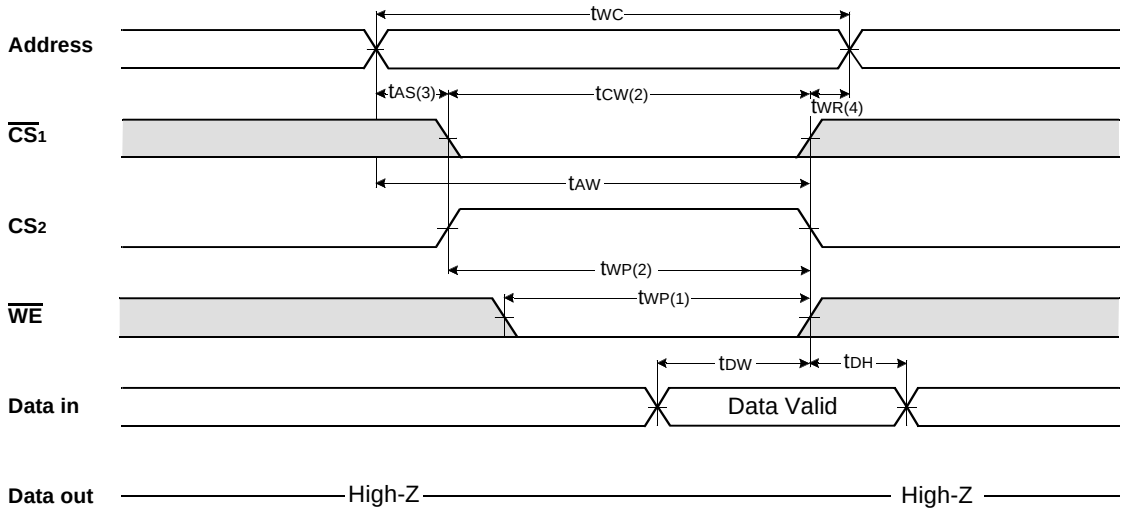
TIMING WAVEFORM OF WRITE CYCLE(1) ($\overline{WE}$ Controlled)



TIMING WAVEFORM OF WRITE CYCLE(2) ($\overline{CS_1}$ Controlled)



TIMING WAVEFORM OF WRITE CYCLE(3) ($\overline{CS_1}$ Controlled)

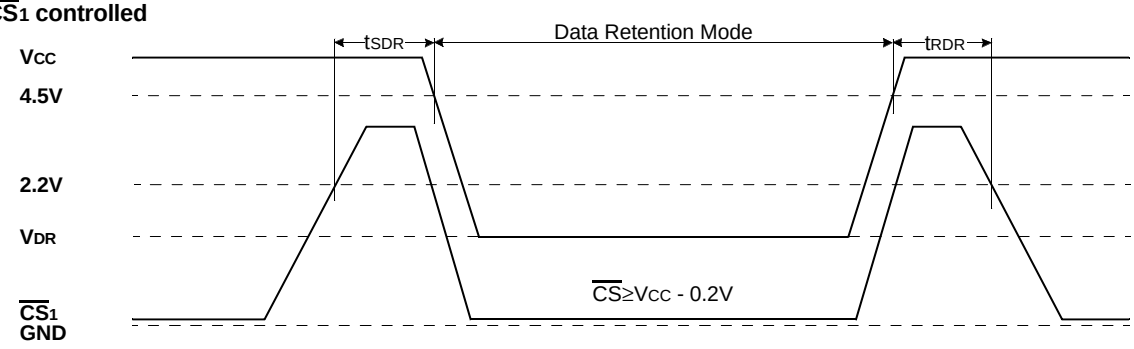


NOTES (WRITE CYCLE)

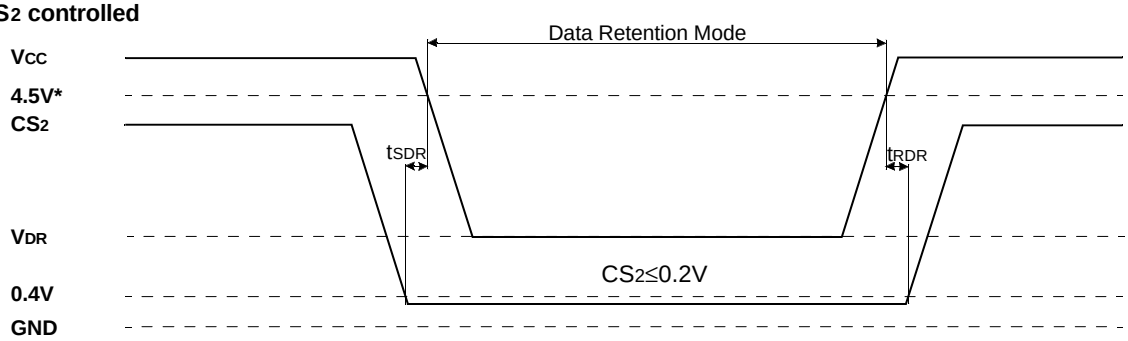
1. A write occurs during the overlap of a low $\overline{CS_1}$, a high CS_2 and a low $\overline{WE}$. A write begins at the latest transition among $\overline{CS_1}$ goes low, CS_2 going high and $\overline{WE}$ going low : A write end at the earliest transition among $\overline{CS_1}$ going high, CS_2 going low and $\overline{WE}$ going high, t_{WP} is measured from the begining of write to the end of write.
2. t_{CW} is measured from the $\overline{CS_1}$ going low or CS_2 going high to the end of write.
3. t_{AS} is measured from the address valid to the beginning of write.
4. t_{WR} is measured from the end of write to the address change. $t_{WR(1)}$ applied in case a write ends as $\overline{CS_1}$ or $\overline{WE}$ going high $t_{WR(2)}$ applied in case a write ends as CS_2 going to low.

DATA RETENTION WAVE FORM

$\overline{CS_1}$ controlled



CS_2 controlled



PACKAGE DIMENSIONS

Units : Millimeters(Inches)

32-THIN SMALL OUTLINE PACKAGE TYPE I (0820F)